

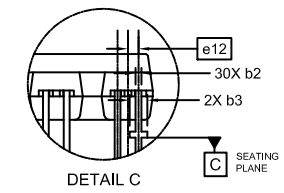
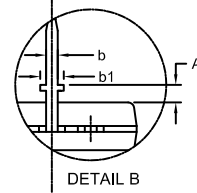
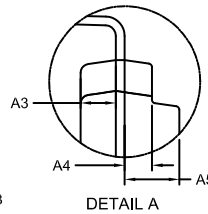
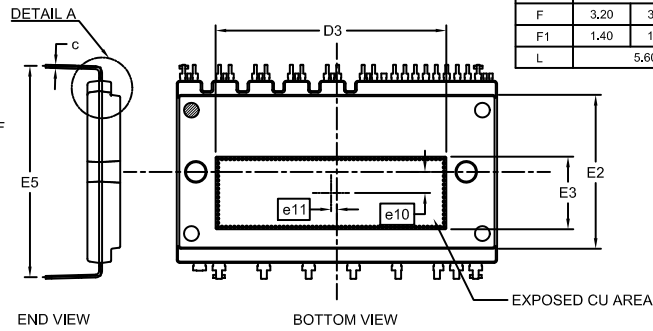
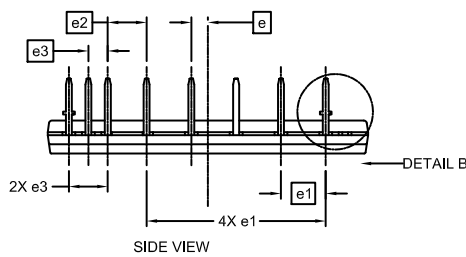
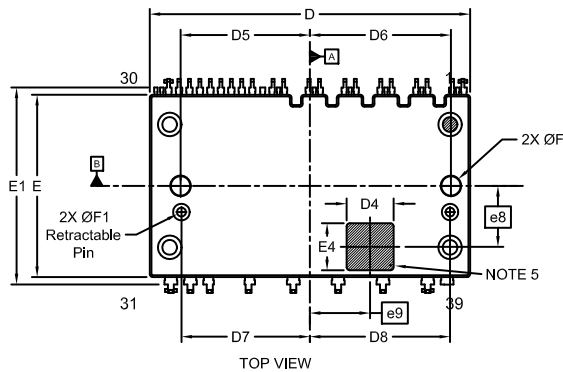
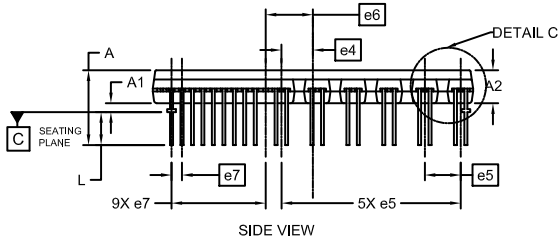
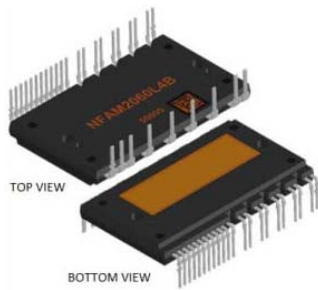
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



DIP39, 54.5x31.0 EP-2 CASE MODGX ISSUE O

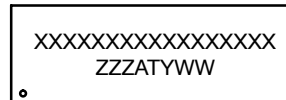
DATE 02 APR 2019



DIM	MILLIMETERS			DIM	MILLIMETERS		
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.
A	12.20	12.7	13.2	E	30.90	31.00	31.10
A1	1.00	1.50	2.00	E1	33.50 REF		
A2	5.50	5.60	5.70	E2	26.14 REF		
A3	2.00 REF			E3	12.35 REF		
A4	1.55 REF			E4	8.00 REF		
A5	3.10 REF			E5	35.40	35.90	36.40
b	0.90	1.00	1.10	e	2.81 REF		
b1	1.90	2.00	2.10	e1	7.62 BSC		
b2	0.40	0.50	0.60	e2	6.60 BSC		
b3	1.40	1.50	1.60	e3	3.30 BSC		
c	0.50 REF			e4	5.35 REF		
D	54.40	54.50	54.60	e5	6.10 BSC		
D3	39.25 REF			e6	8.02 REF		
D4	8.00 REF			e7	1.78 BSC		
D5	22.00 REF			e8	10.35 REF		
D6	24.00 REF			e9	10.25 REF		
D7	21.85 REF			e10	3.60 REF		
D8	23.85 REF			e11	1.00 REF		
				e12	0.89 BSC		
F	3.20	3.30	3.40				
F1	1.40	1.50	1.60				
L	5.60 REF						

- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
 - CONTROLLING DIMENSION: MILLIMETERS
 - DIMENSION b and c APPLY TO THE PLATED LEADS AND ARE MEASURED BETWEEN 1.00 AND 2.00 FROM THE LEAD TIP.
 - POSITION OF THE LEAD IS DETERMINED AT THE BASE OF THE LEAD WHERE IT EXITS THE PACKAGE BODY.
 - AREA FOR 2D BAR CODE.
 - SHORTENED/CUT PINS ARE 2,5,8,11,14,17,19,29, 30 AND 39.

GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
 ZZZ = Assembly Lot Code
 AT = Assembly & Test Location
 Y = Year
 WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	DIP39, 54.5x31.0 EP-2	PAGE 1 OF 1

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